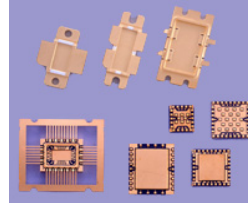


Packaging Materials



Chip Supply

- Die Distribution
- Value Added Processing
- Form Factor Reduction
- CM Packaging



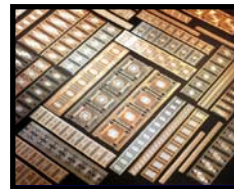
SMI-ED

- Ceramic Packages
- Power RF Packages
- Optical Device
- LED Packages



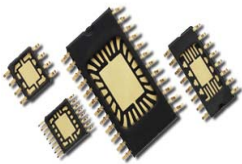
Access

- Multi-layer Substrates
- "Coreless" Technology



SMM-AP

- Etch/Stamp Lead Frames
- Plating
- Laminate Substrates



Sempac

- Open Cavity Plastic Packages
- Lids



RGT, Inc.

- 6"/8"/12" Wafer Frames
- Stainless Steel
- Plastic



Henkel

- D/A Adhesives
- Underfills
- Encapsulents
- Mold Compounds



SMM-MEM

- Au Bonding Wire



Keaco

- Carrier/Cover Tape
- Reels



Quantum Sphere

- Nano Metal Powders
- Application Development

Assembly Equipment



Hanmi Semiconductor

- Assembly Equipment
- Molding/Marking/Ball Placement/Singulation



Disco Hi-Tech

- Wafer Grinding
- Saw Singulation
- Laser Singulation



Applied MST

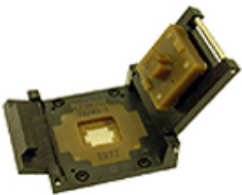
- Molecular Vapor Deposition
- Superior to CVD
- Anti-Stiction / Moisture Barrier Coatings



Topcon

- Wafer Inspection Systems
- Manual / Automated

Test Materials / Equipment



Azimuth Electronics

- Test & Burn-in Sockets
- Machined or Molded



WEB Technology

- Turret Test Handlers
- Bubble Testers
- Centrifuges & Inserts



Galden Test Fluids

- Leak Detection Fluids
- Thermal Shock Fluids
- Liquid Burn-In